

REMARKS

This AMENDMENT UNDER 37 CFR 1.111 is filed in reply to the outstanding Office Action of December 7, 2004, and is believed to be fully responsive thereto for reasons set forth below in greater detail.

Claims 1-3, 7 and 9-12 are pending in this case. Claim 1 is in a form as previously amended in applicants prior response submitted September 8, 2004 in response to the Office Action issued July 8, 2004.

In the present Office Action, the Examiner rejected Claims 1-3, 7 and 9-12 under 35 U.S.C. §112, first paragraph, as allegedly non-enabling. The Examiner particularly alleged that the added recitation “...said center portion is isolated and spaced from immediately adjacent photolithography produced features on said semiconductor substrate, other than said two end portions, by a spacing equal to at least twice said minimum design width...” includes subject matter not described in the specification in such a way as to reasonably convey to a skilled artisan that the inventor(s) had possession of the claimed invention.

Applicants respectfully disagree.

The prior response submitted on September 8, 2004 indicated that original support for these limitations was provided in Figures 6 and 7. However, Examiner has indicated that Figures 6 and 7 do not show said center portion is isolated and spaced from immediately adjacent photolithography produced features on said semiconductor substrate.

Applicants submit that this is clearly described with reference to the specification description in support of Figure 7 as described on page 9, lines 2-7.

For instance, the passage found in the specification states that the spacing between the "center portion", i.e., referring to link portion 13 of width W2 in Figure 7, and the "end portions", i.e., referring to lines 101, 102 which comprise the "immediately adjacent photolithography produced features on said semiconductor substrate" having minimum width W1 (see specification on page 8, lines 25-26) is sufficient to prevent the end portions from serving as a heat sink, which would adversely serve to increase the amount of joule heating required to change the electrical property. The present specification further describes at page 9, lines 6 and 7 that for some semiconductor technologies, for example, the minimum width can be approximately 0.13 microns, and the spacing is at least approximately 0.5 microns.

Thus, the minimum width as claimed is 0.13 microns (in some semiconductor technologies) and the spacing from the center portion (that is isolated and spaced from immediately adjacent photolithography produced features —i.e., conductive lines 101, 102) is at least approximately 0.5 microns, or, in another words, a spacing equal to at least twice said minimum design width (i.e., 0.5 microns is at least twice the minimum design width of 0.13 microns) as set forth in amended Claim 1.

Thus, respectfully, clear support is found in the specification for the added recitations to amended Claim 1 as provided in applicants' prior response of September 8, 2004. Accordingly, the Examiner is respectfully requested to withdraw the rejection of Claim 1 under 35 U.S.C. §112, first paragraph grounds, as allegedly not enabled.

This application is now believed to be in condition for allowance, and a Notice of Allowance is respectfully requested. If the Examiner believes a telephone conference might expedite prosecution of this case, it is respectfully requested that he call applicant's attorney at (516) 742-4343.

Respectfully submitted,



Steven Fischman
Registration No. 34,594

SCULLY, SCOTT, MURPHY & PRESSER
400 Garden City Plaza, Suite 300
Garden City, New York 11530
(516) 742-4343
SF:gc